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WHAT IS CLAIMED IS:

1	1.	A circuit sneet, comprising:			
2	a sul	a substrate; and			
3	wells disposed on the substrate and operable to hold respective conductive				
4	polymers th	olymers that form circuit devices.			
1	2.	The sheet of claim 1, further comprising:			
2	a firs	a first set of ridges formed in a first direction on the substrate;			
3	a se	a second set of ridges formed in a second direction on the substrate, the			
4	second dire	ond direction being substantially perpendicular to the first direction; and			
5	whei	wherein the wells are defined by respective intersections of the first and			
6	second sets	ond sets of ridges.			
1	3.	The sheet of claim 1 wherein the substrate is flexible.			
1	4.	A circuit sheet, comprising:			
2	a su	a substrate; and			
3	a tre	a treatment disposed on regions of the substrate and operable to limit the			
4	sizes of cor	s of conductive-polymer dots printed onto the regions.			
1	5.	An electronic device, comprising:			
2	a su	a substrate;			
3	cond	conductive polymer dots disposed on the substrate in predetermined locations;			
4	and				
5	a co	a connection layer that interconnects the dots to form a circuit.			
1	6.	The circuit electronic device of claim 5, further comprising a display			
2	disposed on the connection layer and operable to be driven by the circuit.				
1	7.	The circuit of claim 5 wherein at least one of the conductive polymer			
2	dots comprises polymer poly-paraphenylene vinylene poly-paraphenylene (PPP).				
1	8.	The circuit of claim 5 further comprising wells formed on the substrate			
2	in the predetermined locations and holding the dots.				
1	9.	The circuit of claim 5 wherein the predetermined locations of the			

substrate are treated to limit the size of the dots.

1	10.	A circuit sheet, comprising:		
2	a substrate; and			
3	circuit components disposed on the substrate and formed from a conductive			
4	polymer.			
1	11.	The circuit sheet of claim 10 wherein the circuit components are		
2	isolated from one and other.			
1	12.	A circuit, comprising:		
2	a su	a substrate;		
3	circu	circuit components disposed on the substrate and formed from a conductive		
4	polymer; and			
5	conductive traces disposed on the substrate and interconnecting the circuit			
6	component	mponents in a predetermined topology.		
1	13.	The circuit of claim 12, further comprising a display disposed on the		
2	substrate a	substrate and operable to be driven by the interconnected circuit components.		
1	14.	A method, comprising:		
2	form	forming a first set of ridges on a substrate; and		
3	form	forming a second set of ridges on the substrate such that the first and second		
4	sets of ridges define wells operable to receive and hold respective conductive			
5	polymers.			
1	15.	The method of claim 14 wherein forming the first and second sets of		
2	ridges comprise printing the first and second sets of ridges onto the substrate.			
1	16.	The method of claim 14 wherein forming the first and second sets of		
2	ridges comprise stamping the first and second sets of ridges onto the substrate.			
1	17.	The method of claim 14 wherein forming the second set of ridges		
2	comprises forming the ridges of the second set substantially perpendicular to the			
3	ridges of the first set.			
1	18.	A method, comprising:		
2	forming circuit components from dots of a conductive polymer on a substrate			
3	and			
4	inte	connecting the circuit components to form a circuit.		

1	19.	The method of claim 18 wherein forming circuit components comprises	
2	filling wells on the substrate with the conductive polymer.		

- 1 20. The method of claim 18 wherein forming circuit components comprises 2 treating the substrate to limit the sizes of the dots.
- 1 21. A method, comprising:
- 2 acquiring a substrate on which are disposed conductive polymer circuit
- 3 components; and
- 4 interconnecting the conductive-polymer circuit components to form a circuit.